

# Bill of Materials

TI DESIGNS

TIDA-00616

Item	Qty	Reference	Value	Part Description	Manufacturer Part Number	PCB Footprint
1	3	C1, C10, C14	4.7 uF	CAP, CERM, 4.7uF, 6.3V, +/-20%, X5R, 0402	1005X5R0J475M050B	402
2	1	C2	2.2 uF	CAP, CERM, 2.2 uF, 6.3 V, +/- 10%, X6S, 0603	GRM188C80J225KE19D	603
3	2	C3, C18	0.01 uF	CAP, CERM, 0.01uF, 10V, +/-10%, X5R, 0402	GRM155R61A103KA01F	402
4	4	C4, C6, C7, C9	0.1 uF	CAP, CERM, 0.1 uF, 6.3 V, +/- 10%, X5R, 0402	C1005X5R0J104K	0402L
5	2	C5, C8	10 uF	CAP, CERM, 10 uF, 25 V, +/- 20%, X5R, 0603	C1608X5R1E106M080A	0603L
6	3	C11, C12, C13	0.1 uF	CAP, CERM, 0.1uF, 10V, +/-10%, X7R, 0402	GRM155R71A104KA01F	0402L
7	1	C19	100 uF	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	C1210C107M9PACTU	1210
8	1	D1	4.7 V	Diode, Zener, 4.7V, 300mW, SOD-523	BZT52C4V7T-7	SOD-523
9	6	FID1, FID2, FID3, FID4, FID5, FID6	-	Fiducial mark. There is nothing to buy or mount.	Fiducial	Fiducial10-20
10	1	GND	-	Test Point, Miniature, Black, TH	5001	Keystone5001
11	2	J1, J2	-	Header, 100mil, 3x1, Tin, TH	5-146278-3	TE_5-146278-3
12	2	J3, J4	-	Header, 100mil, 2x1, Tin plated, TH	90120-0122	CONN_90120-0122
13	2	J5, J6	-	Receptacle 100mil 10x1, Tin, TH	PPTC101LFBN-RC	CONN_PPTC101LFBN-RC
14	1	J7	-	Receptacle, 100mil, 4x1, Gold, R/A, TH	PPPC041LGBN-RC	SULLINS_PPPC041LGBN-RC
15	1	J8	-	Receptacle, 100mil, 3X1, TH	PPTC031LFBN-RC	Sullins_PPTC031LFBN-RC
16	5	JP1, JP2, JP3, JP4, JP5	-	Header, 50mil, 3x1, Gold, TH	850-10-003-10-001000	I-Max_850-10-003-10-001000
17	1	JP6	-	Header, 100mil, 2x1, Tin, TH	5-146278-2	TE_5-146278-2
18	1	L2	22 uH	Inductor, Shielded Drum Core, Ferrite, 22uH, 0.83A, 0.36 ohm, SMD	LPS4018-223MLB	LPS4018
19	1	Q1	-	MOSFET, P-CH, -50V, -0.13A, SOT-23	BSS84-7-F	SOT-23
20	1	Q2	-	MOSFET, N-CH, 60 V, 0.17 A, SOT-23	2N7002-7-F	SOT-23
21	6	R1, R9, R10, R11, R14, R15	1 M	RES, 1.00 M, 1%, 0.063 W, 0402	CRCW04021M00FKED	0402L
22	4	R4, R5, R6, R8	49.9 K	RES, 49.9k ohm, 1%, 0.063W, 0402	CRCW040249K9FKED	0402L
23	2	R12, R13	2.43	RES, 2.43, 1%, 0.063 W, 0402	CRCW04022R43FKED	0402L
24	2	R16, R17	1 k	RES, 1.00 k, 1%, 0.1 W, 0402	ERJ-2RKF1001X	0402L
25	1	R20 - ROV1	5.76 M	RES, 5.76 M, 1%, 0.063 W, 0402	CRCW04025M76FKED	0402L
26	1	R21 - ROV2	7.5 M	RES, 7.50 M, 1%, 0.063 W, 0402	CRCW04027M50FKED	0402L
27	1	R22 - ROK1	5.36 M	RES, 5.36 M, 1%, 0.063 W, 0402	CRCW04025M36FKED	0402L
28	1	R23 - ROK2	6.98 M	RES, 6.98 M, 1%, 0.063 W, 0402	CRCW04024M99FKED	0402L
29	1	R24 - ROK3	0.877 M	RES, 0.887 M, 1%, 0.063 W, 0402	CRCW04021M27FKED	0402L
30	1	R25 - ROUT1	6.49 M	RES, 6.49 M, 1%, 0.063 W, 0402	CRCW04026M49FKED	0402L
31	1	R26 - ROUT2	6.65 M	RES, 6.65 M, 1%, 0.063 W, 0402	CRCW04026M65FKED	0402L
32	1	U1	-	Imported	TPS79633 DCQ 6	DCQ6
33	1	U2	-	Nano Power Programmable Timer, DGS0010A	TPL5100DGS	DGS0010A_N
34	2	U3, U4	-	Low-Voltage H-Bridge IC With LDO Regulator, RGY0024B	DRV8850RGY	RGY0024B
35	1	U5	-	Ultra Low Power Harvester Power Management IC with Boost Charger, and Nano-Powered Buck Converter, RGR0020A	BQ25570RGR	RGR0020A
36	1	U6	-	Imported	SN74AUP1G74 DCU	DCU8
37	2	VBAT, VCC	-	Test Point, Miniature, Red, TH	5000	Keystone5000

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